

## TISP® Telecom Overvoltage Protectors.

TISP® products in SMD packages meet the requirements of JEDEC J-STD-020 MSL 1 when assembled using the following solder profile.

### Lead Free SMD Solder Reflow Profile

Profile Feature	Condition
Preheat 150 °C ( $T_{smin}$ ) to 200 °C ( $T_{smax}$ )	Time 60 - 150 s.
Average Ramp-Up Rate ( $T_{smax}$ to $t_p$ )	3 °C/second max.
Time maintained above liquidus ( $t_L$ ) 217 °C	60 - 150 s
Time within 5 °C of Peak Temperature ( $t_p$ )	20 - 40 s
Peak temperature ( $t_p$ )	260 °C +0/-5 °C max
Ramp-Down Rate	6 °C/second max
Time from 25 °C to Peak Temperature	8 minutes max

